

# Material Declaration Report

Package Type:	SOT23 6L
Pericom Package Code:	T6(Pb-free)
RoHS Compliance:	Yes
Applicable Exemption:	N/A

Component Weight (mg):	17.227
Termination Plating:	Matte Tin
JESD 97 Pb-free Category:	e3
Plating Thickness (um):	10-20
Tin Whisker Mitigation:	Anneal, 150C/1hr

MSL Rating:	1
Peak Body Temp (C):	260
Max Time (sec):	40
Reflow Cycles:	3
Rev Date:	6/4/2008

## Homogeneous Material Declaration

MATERIAL ITEM	MATERIAL WEIGHT(mg)	ASSEMBLY SUBCON	MATERIAL COMPOSITION	CAS NO.	COMPOSITION %	COMPOSITION WEIGHT(mg)
MOLD COMPOUND	8.396	UNI-M and UTL	Silica Fused	60676-86-0	88.000	7.3885
			Epoxy Resin	Proprietary	5.000	0.4198
			Phenolic Resin	Proprietary	4.500	0.3778
			Epoxy, Cresol Novolac	29690-82-2	2.000	0.1679
			Carbon Black	1333-86-4	0.500	0.0420
LEADFRAME	7.676		Copper	7440-50-8	97.021	7.4473
			Iron	7439-89-6	2.350	0.1804
			Silver	7440-22-4	0.453	0.0348
			Zinc	7440-66-6	0.111	0.0085
			Phosphorus	7723-14-0	0.065	0.0050
SILICON DIE	0.471		Silicon (Si)	7440-21-3	99.192	0.4672
			Non-hazardous Metal	Proprietary	0.808	0.0038
DIE ATTACH EPOXY	0.052	UTL	Epoxy Resin	129915-35-1	35.000	0.0182
			Metal Oxide	Proprietary	32.000	0.0166
			Glycol Ethers	Proprietary	22.000	0.0114
			Curing Agent & Hardener	Proprietary	8.000	0.0042
		Treated Silica	7631-86-9	3.000	0.0016	
		UNI-M	Crystalline Silica	14808-60-7	45.000	0.0234
			Phenolic Resin	28064-14-4	30.000	0.0156
1, 4-Bis (2, 3-Epoxypropoxy) butane	2425-79-8		20.000	0.0104		
Alvosulfone	80-08-0	5.000	0.0026			
GOLD WIRE	0.088		Gold(Au)	7440-57-5	99.990	0.0880
			Impurities	-	0.010	0.0000
SOLDER PLATING	0.544		Tin (Sn)	7440-31-5	99.990	0.5439
			Impurity	-	0.010	0.0001

NOTE: The device contents disclosed are approximated and are based on engineering estimates.

17.2790

## 3rd Party Analysis Results (PPM)

MATERIAL	Pb	Hg	Cr+6	Cd	PBB	PBDE
Mold Compound	<2	<2	<2	<2	<5	<5
Leadframe	<50	<2	<2	<2	<5	<5
Device Silicon Die	<2	<2	<2	<2	<5	<5
Die Attach Epoxy	<2	<2	<2	<2	<5	<5
Gold Wire	<2	<2	<2	<2	<5	<5
Solder Plating	<50	<2	<2	<2	<5	<5

## ROHS MATERIAL COMPOSITION DECLARATION

EU RoHS Directive 2002/95/EC  and  China RoHS Directive SJ/T11363-2006	<p><b>Declaration Statement:</b> Quantity limit of 0.1% (1000 PPM) by mass in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium(Cr+6), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE); and Quantity limit of 0.01% (100 PPM) for Cadmium</p> <table border="1"> <thead> <tr> <th>Pb</th> <th>Hg</th> <th>Cr+6</th> <th>Cd</th> <th>PBB</th> <th>PBDE</th> </tr> </thead> <tbody> <tr> <td>&lt;1000ppm</td> <td>&lt;1000ppm</td> <td>&lt;1000ppm</td> <td>&lt;100ppm</td> <td>&lt;1000ppm</td> <td>&lt;1000ppm</td> </tr> <tr> <td>O</td> <td>O</td> <td>O</td> <td>O</td> <td>O</td> <td>O</td> </tr> </tbody> </table>	Pb	Hg	Cr+6	Cd	PBB	PBDE	<1000ppm	<1000ppm	<1000ppm	<100ppm	<1000ppm	<1000ppm	O	O	O	O	O	O
	Pb	Hg	Cr+6	Cd	PBB	PBDE													
<1000ppm	<1000ppm	<1000ppm	<100ppm	<1000ppm	<1000ppm														
O	O	O	O	O	O														
<p>O: Indicates that this toxic or hazardous substance contained in all of the homogeneous materials for this part is below the limit requirement in SJ/T11363-2006. X: Indicates that this toxic or hazardous substance contained in at least one of the homogeneous materials used for this part is above the limit requirement in SJ/T11363-2006.</p>																			